MOSFET - SiC Power, Single N-Channel 900 V, 60 mΩ, 46 A

NTHL060N090SC1

Features

- Typ. $R_{DS(on)} = 60 \text{ m}\Omega @ V_{GS} = 15 \text{ V}$
- Typ. $R_{DS(on)} = 43 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge (typ. $Q_{G(tot)} = 87 \text{ nC}$)
- Low Effective Output Capacitance (typ. Coss = 113 pF)
- 100% UIL Tested
- These Devices are RoHS Compliant

Typical Applications

- UPS
- DC/DC Converter
- Boost Inverter

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage			V_{DSS}	900	٧
Gate-to-Source Voltage			V _{GS}	+22/-8	V
Recommended Operation Values of Gate-to-Source Voltage	T _C < 175°C		V_{GSop}	+15/-5	V
Continuous Drain Current R _{0JC}	Steady State	T _C = 25°C	I _D	46	Α
Power Dissipation $R_{\theta JC}$	Olaic		P_{D}	221	V
Continuous Drain Current R _{0JC}	Steady State	T _C = 100°C	Ι _D	32	Α
Power Dissipation $R_{\theta JC}$	Siale		P_{D}	110	W
Pulsed Drain Current (Note 2)	T _A	= 25°C	I _{DM}	184	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	ç
Source Current (Body Diode)			Is	22	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 18 A, L = 1 mH) (Note 3)			E _{AS}	162	mJ

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Note 1)	$R_{\theta JC}$	0.68	°C/W
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	40	°C/W

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. E_{AS} of 162 mJ is based on starting $T_J = 25^{\circ}C$; L = 1 mH, I_{AS} = 18 A, V_{DD} = 100 V, V_{GS} = 15 V.

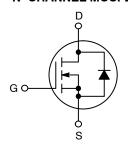


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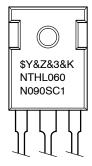
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
900 V	84 mΩ @ 15 V	46 A

N-CHANNEL MOSFET





MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week)

&K = Lot

NTHL060N090SC1 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS

	Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Drain-Do-Source Breaktown Voltage Temperature Coefficient Temp	OFF CHARACTERISTICS						
Drain-Do-Source Breaktown Voltage Temperature Coefficient Temp	Drain-to-Source Breakdown Voltage	V _{(BB)DSS}	V _{GS} = 0 V, I _D = 1 mA	900			V
Vos = 0 V, Vos = 900 V, T_J = 175°C 250 250 251 μA 250 Vos = 122/-8 V, Vos = 90 V T_J = 175°C 251 μA 250 251 μA 250 251 μA 251 μ		†			574		mV/°C
A continue Leakage Current Indicate I	Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 900 V, T _J = 25°C			100	μΑ
Concession Co			V _{GS} = 0 V, V _{DS} = 900 V, T _J = 175°C			250	
Recommended Gate Voltage V _{GS} (th) V _{GS} = V _{DS} , I _D = 5 mA 1.8 2.7 4.3 V	Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +22/-8 V, V _{DS} = 0 V			±1	μΑ
Recommended Gate Voltage Voltag							1
Peccommended Gate Voltage VGOP	Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$, $I_D = 5 \text{ mA}$	1.8	2.7	4.3	V
Forward Transconductance Gras Vogs = 16 V, Ip = 20 A, Ty = 25°C 43 135	Recommended Gate Voltage			-5		+15	V
VGS = 18 V, Ip = 20 A, T _J = 25°C 43 135	Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 20 A, T _J = 25°C		60	84	mΩ
Forward Transconductance GFS VDS = 20 V, ID = 20 A 17 17 S S			V _{GS} = 18 V, I _D = 20 A, T _J = 25°C		43		
Forward Transconductance GFS VDS = 20 V, ID = 20 A 17 17 S S			V _{GS} = 15 V, I _D = 20 A, T _J = 175°C		76	135	
Input Capacitance	Forward Transconductance	9FS			17		S
Output Capacitance Coss Reverse Transfer Capacitance Coss Cass Cass Gate Charge V _{GS} = 0 V, f = 1 MHz, V _{DS} = 450 V 113 Introduction of the cost of	CHARGES, CAPACITANCES & GATE	RESISTANCE			l		
Output Capacitance	Input Capacitance	C _{ISS}			1770		pF
Reverse Transfer Capacitance CRSS Total Gate Charge QG(tot) Threshold Gate Charge QG(tot) Gate -to -Source Charge QGS Gate -to -Drain Charge QGB Gate Resistance RG f = 1 MHz SWITCHING CHARACTERISTICS Turn-On Delay Time td(en) Fall Time tf Turn-Off Delay Time td(eff) Turn-Off Switching Loss EON Turn-Off Switching Loss ETOT Total Switching Loss ETOT Total Switching Loss Continuous Drain-to-Source Diode Forward Current (Note 2) Forward Diode Voltage VSD VGS = -5/15 V, VDS = 720 V, VDS	Output Capacitance		V _{GS} = 0 V, f = 1 MHz, V _{DS} = 450 V		113		
Total Gate Charge	Reverse Transfer Capacitance				11		
Threshold Gate Charge	Total Gate Charge				87		nC
Gate-to-Source Charge Q _{GS} Q _{GD} Q _G	Threshold Gate Charge		-		17		
Gate - to - Drain Charge QGD Gate Resistance RG f = 1 MHz 3.0 Ω Ω	Gate-to-Source Charge		$V_{GS} = -5/15 \text{ V}, V_{DS} = 720 \text{ V}, I_D = 10 \text{ A}$		27		
Sate Resistance R _G f = 1 MHz 3.0 Ω			-		26		
Turn-On Delay Time td(on) Turn-Off Delay Time td(off) Turn-Off Delay Time tq(off) Turn-Off Switching Loss E _{ON} Turn-Off Switching Loss E _{OFF} E _{TOT} E _{TOT} Turn-Off Switching Loss E _{TOT} Turn-Off Switching Loss E _{TOT}			f = 1 MHz		3.0		Ω
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	SWITCHING CHARACTERISTICS						
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Turn-On Delay Time	t _{d(on)}			22	40	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Rise Time		-		33	66	
Fall Time t_f $I_D = 20 A, R_G = 2.5 \Omega,$ $I_D = 20 A, I_D = 2.5 \Omega,$ $I_D = 20 A, I_D = 2.5 \Omega,$ $I_D = 20 A, $	Turn-Off Delay Time		 		31	74	
Turn-On Switching Loss E_{ON} Turn-Off Switching Loss E_{OFF} Total Switching Loss E_{TOT} DRAIN-SOURCE DIODE CHARACTERISTICS Continuous Drain-to-Source Diode Forward Current (Note 2) Pulsed Drain-to-Source Diode Forward Current (Note 2) Forward Diode Voltage V_{SD} Reverse Recovery Time V_{RR} Reverse Recovery Charge V_{RR} Reverse Recovery Energy V_{RR} Peak Reverse Recovery Current V_{RR} Charge Time V_{RR} Inductive Load 464 464 487 180 487 Pulsed Drain-to-Source Diode ForVal87 487 Pogs = -5 V, TJ = 25 °C 184 A VGS = -5 V, TJ = 25 °C 184 A VGS = -5 V, TJ = 25 °C 184 A A A A A A A A A A A A A	•		$V_{GS} = -5/15 \text{ V}, V_{DS} = 720 \text{ V},$ $I_{D} = 20 \text{ A}. R_{G} = 2.5 \Omega.$		11	20	
Turn-Off Switching Loss E_{OFF} Total Switching Loss E_{TOT} DRAIN-SOURCE DIODE CHARACTERISTICS Continuous Drain-to-Source Diode Forward Current Pulsed Drain-to-Source Diode Forward Current (Note 2) Forward Diode Voltage V_{SD} Reverse Recovery Time V_{RR} Reverse Recovery Charge V_{RR} Reverse Recovery Energy V_{RR} Peak Reverse Recovery Current V_{RR} Charge Time V_{RR} Total Switching Loss V_{RR} $V_$	Turn-On Switching Loss				464		μJ
Total Switching Loss E_{TOT} 487 DRAIN-SOURCE DIODE CHARACTERISTICS Continuous Drain-to-Source Diode Forward Current	Turn-Off Switching Loss		-		23		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Total Switching Loss		-		487		
Forward Current $V_{GS} = -5 \text{ V}, \ I_J = 25 ^{\circ}\text{C}$ Pulsed Drain—to—Source Diode Forward Current (Note 2) $V_{GS} = -5 \text{ V}, \ T_J = 25 ^{\circ}\text{C}$ Forward Diode Voltage V_{SD} $V_{GS} = -5 \text{ V}, \ I_{SD} = 10 \text{ A}, \ T_J = 25 ^{\circ}\text{C}$ Reverse Recovery Time t_{RR} 18 ns Reverse Recovery Charge Q_{RR} 84 nC Reverse Recovery Energy E_{REC} $V_{GS} = -5/15 \text{ V}, \ I_{SD} = 30 \text{ A}, \ dI_{S}/dt = 1000 \text{ A}/\mu\text{s}, \ V_{DS} = 720 \text{ V}$ Charge Time t_{A} 10 ns	DRAIN-SOURCE DIODE CHARACTER				<u> </u>		I
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		I _{SD}	V _{GS} = -5 V, T _J = 25°C			22	А
Reverse Recovery Time t_{RR} Reverse Recovery Charge Q_{RR} Reverse Recovery Energy E_{REC} Peak Reverse Recovery Current I_{RRM} Charge Time t_a 18 18 ns 18 ns 18 nc 10 $V_{QS} = -5/15 \text{ V}, I_{SD} = 30 \text{ A}, I_{SD} = 30 \text{ A}, I_{SD} = 720 \text{ V}$		I _{SDM}	V _{GS} = -5 V, T _J = 25°C			184	Α
Reverse Recovery Time t_{RR} Reverse Recovery Charge Q_{RR} Reverse Recovery Energy E_{REC} Peak Reverse Recovery Current I_{RRM} Charge Time t_a	Forward Diode Voltage	V _{SD}	V _{GS} = -5 V, I _{SD} = 10 A, T _J = 25°C		3.9		V
Reverse Recovery Charge Q_{RR} Reverse Recovery Energy E_{REC} Peak Reverse Recovery Current I_{RRM} Charge Time $V_{QS} = -5/15 \text{ V}, I_{SD} = 30 \text{ A}, \\ dI_{S}/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 720 \text{ V}$ 1.0 μJ 9.0 A	Reverse Recovery Time		-		18		ns
Reverse Recovery Energy E_{REC} $V_{GS} = -5/15 \text{ V}, I_{SD} = 30 \text{ A}, \\ dI_{S}/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 720 \text{ V}$ 9.0 A Charge Time t_a 10 ns	Reverse Recovery Charge		1		84		nC
Peak Reverse Recovery Current I_{RRM} $dI_{S}/dt = 1000 \text{ A/µs}, V_{DS} = 720 \text{ V}$ 9.0 A Charge Time t_{a} 10 ns	Reverse Recovery Energy		Voc = -5/15 V lon - 30 A		1.0		μJ
Charge Time t _a 10 ns					9.0		Α
	Charge Time		1		10		ns
		t _b	1		8.0		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

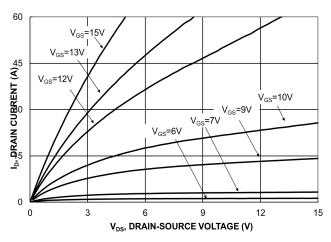


Figure 1. On-Region Characteristics

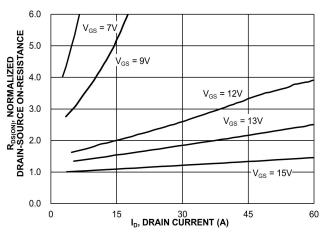


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

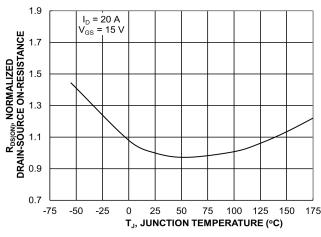


Figure 3. On–Resistance Variation with Temperature

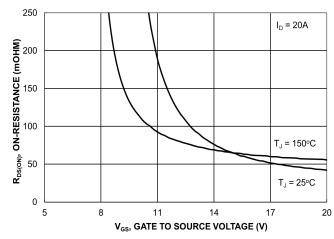


Figure 4. On-Resistance vs. Gate-to-Source Voltage

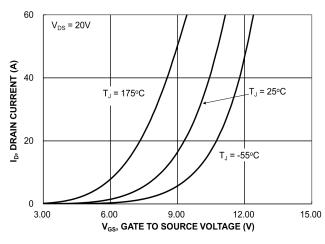


Figure 5. Transfer Characteristics

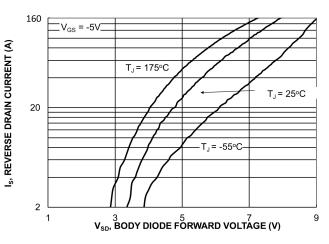


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS

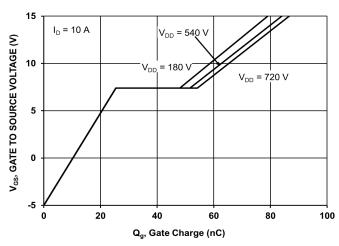


Figure 7. Gate-to-Source Voltage vs. Total Charge

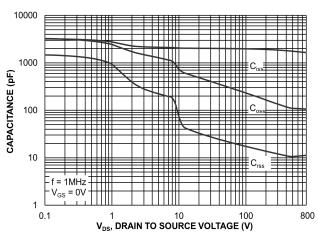


Figure 8. Capacitance vs. Drain-to-Source Voltage

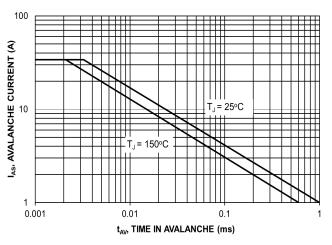


Figure 9. Unclamped Inductive Switching Capability

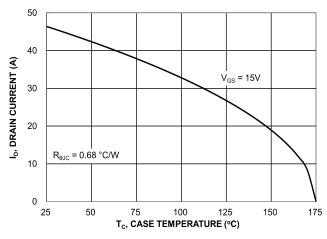


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

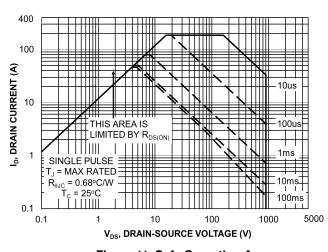


Figure 11. Safe Operating Area

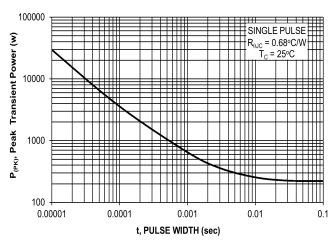


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS

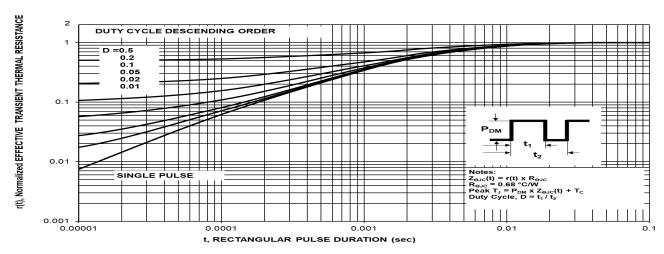
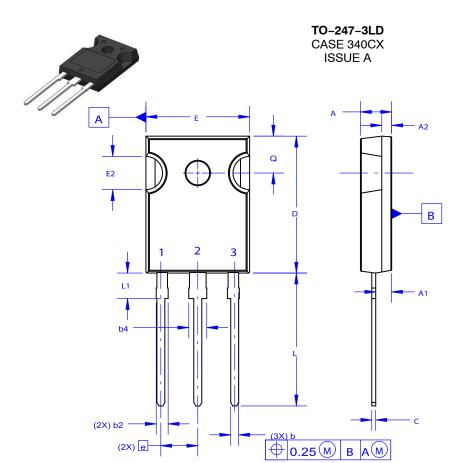


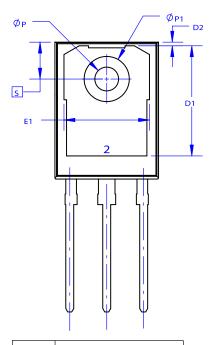
Figure 13. Junction-to-Ambient Thermal Response

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTHL060N090SC1	NTHL060N090SC1	TO-247 Long Lead	Tube	N/A	N/A	30 Units



DATE 06 JUL 2020

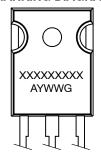


NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " =", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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